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Rosenberger and MultiLane Collaborate to Expand New Interconnect Series (SMPS) to the HSIO Market

Regional subsidiary of the Rosenberger Group, Rosenberger North America (RNA), announced today the launch of its Subminiature Push-On Submicro (SMPS) interconnect series for 224 Gbps/lane application. Initially designed by MultiLane, the collaboration is to help accelerate the development and deployment of the SMPS product series worldwide.

The strict requirements of AI network infrastructures has put pressure on semiconductor and system vendors to secure as much design flexibility as possible to meet tighter timelines and costs.

“We are very excited to bring our SMPS interconnects to this partnership with Rosenberger,” said Toufic Hatem, Interconnect Manager at MultiLane. “MultiLane was first to develop this leading 224Gbps/lane-ready solution, and working with Rosenberger ensures that together, we will be able to scale up production and meet the industry’s demand.”

“Rosenberger is proud to reveal the SMPS product family, enabling 224 Gbps connectivity for the ever-increasing performance and specifications that are required with today's applications in semiconductor, automated test equipment, and other markets/applications,” said Neal Rambhia, Test & Measurement Vice President at RNA. “The SMPS product family will be greatly complimentary to Rosenberger's existing product portfolio.”

The SMPS interconnect series supports a frequency range of up to 110 GHz and is extremely versatile, providing customers options for board-to-board, cable-to-board, or cable-to-cable connections.

View the new website: www.rosenbergerna.com

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